

# ON Semiconductor

## Is Now

# onsemi™

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[www.onsemi.com](http://www.onsemi.com)

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# MJD112 (NPN), MJD117 (PNP)

## Complementary Darlington Power Transistors

### DPAK For Surface Mount Applications

Designed for general purpose power and switching such as output or driver stages in applications such as switching regulators, converters, and power amplifiers.

#### Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Straight Lead Version in Plastic Sleeves (“-1” Suffix)
- Electrically Similar to Popular TIP31 and TIP32 Series
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant\*



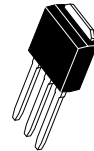
**ON Semiconductor®**

<http://onsemi.com>

**SILICON  
POWER TRANSISTORS  
2 AMPERES  
100 VOLTS, 20 WATTS**

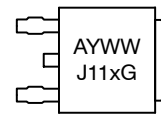


**DPAK  
CASE 369C**

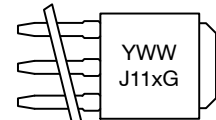


**DPAK-3  
CASE 369D**

#### MARKING DIAGRAMS



DPAK



DPAK-3

A = Assembly Location  
Y = Year  
WW = Work Week  
x = 2 or 7  
G = Pb-Free Package

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## MJD112 (NPN), MJD117 (PNP)

### MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector–Emitter Voltage	$V_{CEO}$	100	Vdc
Collector–Base Voltage	$V_{CB}$	100	Vdc
Emitter–Base Voltage	$V_{EB}$	5	Vdc
Collector Current Continuous Peak	$I_C$	2 4	Adc
Base Current	$I_B$	50	mAdc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	20 0.16	W W/ $^\circ\text{C}$
Total Power Dissipation (Note1) @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	1.75 0.014	W W/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	-65 to +150	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction–to–Case	$R_{\theta JC}$	6.25	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction–to–Ambient (Note 1)	$R_{\theta JA}$	71.4	$^\circ\text{C}/\text{W}$

1. These ratings are applicable when surface mounted on the minimum pad sizes recommended.

## MJD112 (NPN), MJD117 (PNP)

### ELECTRICAL CHARACTERISTICS ( $T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>				
Collector–Emitter Sustaining Voltage (Note 2) ( $I_C = 30\text{ mAdc}$ , $I_B = 0$ )	$V_{CE(sus)}$	100	–	Vdc
Collector Cutoff Current ( $V_{CE} = 50\text{ Vdc}$ , $I_B = 0$ )	$I_{CEO}$	–	20	$\mu\text{Adc}$
Collector Cutoff Current ( $V_{CB} = 100\text{ Vdc}$ , $I_E = 0$ )	$I_{CBO}$	–	20	$\mu\text{Adc}$
Emitter Cutoff Current ( $V_{BE} = 5\text{ Vdc}$ , $I_C = 0$ )	$I_{EBO}$	–	2	mA <sub>dc</sub>
Collector–Cutoff Current ( $V_{CB} = 80\text{ Vdc}$ , $I_E = 0$ )	$I_{CBO}$	–	10	$\mu\text{Adc}$
Emitter–Cutoff Current ( $V_{BE} = 5\text{ Vdc}$ , $I_C = 0$ )	$I_{EBO}$	–	2	mA <sub>dc</sub>
<b>ON CHARACTERISTICS</b>				
DC Current Gain ( $I_C = 0.5\text{ Adc}$ , $V_{CE} = 3\text{ Vdc}$ ) ( $I_C = 2\text{ Adc}$ , $V_{CE} = 3\text{ Vdc}$ ) ( $I_C = 4\text{ Adc}$ , $V_{CE} = 3\text{ Vdc}$ )	$h_{FE}$	500 1000 200	– 12,000 –	–
Collector–Emitter Saturation Voltage ( $I_C = 2\text{ Adc}$ , $I_B = 8\text{ mAdc}$ ) ( $I_C = 4\text{ Adc}$ , $I_B = 40\text{ mAdc}$ )	$V_{CE(sat)}$	– –	2 3	Vdc
Base–Emitter Saturation Voltage ( $I_C = 4\text{ Adc}$ , $I_B = 40\text{ mAdc}$ )	$V_{BE(sat)}$	–	4	Vdc
Base–Emitter On Voltage ( $I_C = 2\text{ Adc}$ , $V_{CE} = 3\text{ Vdc}$ )	$V_{BE(on)}$	–	2.8	Vdc
<b>DYNAMIC CHARACTERISTICS</b>				
Current–Gain – Bandwidth Product ( $I_C = 0.75\text{ Adc}$ , $V_{CE} = 10\text{ Vdc}$ , $f = 1\text{ MHz}$ )	$f_T$	25	–	MHz
Output Capacitance ( $V_{CB} = 10\text{ Vdc}$ , $I_E = 0$ , $f = 0.1\text{ Mhz}$ ) MJD117, NJVMJD117T4G MJD112, NJVMJD112G, NJVMJD112T4G	$C_{ob}$	– –	200 100	pF

2. Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

\*These ratings are applicable when surface mounted on the minimum pad sizes recommended.

# MJD112 (NPN), MJD117 (PNP)

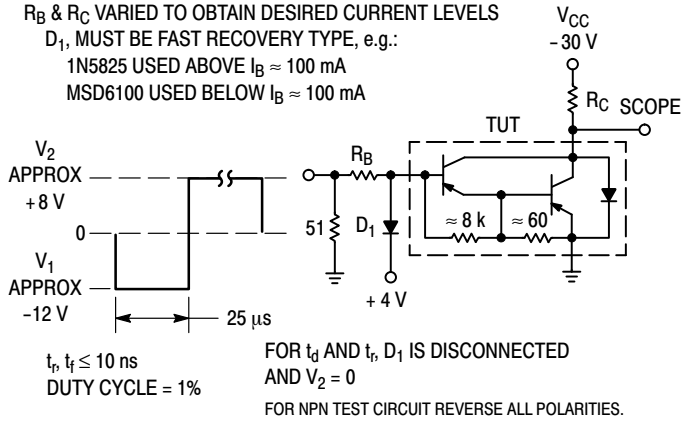


Figure 1. Switching Times Test Circuit

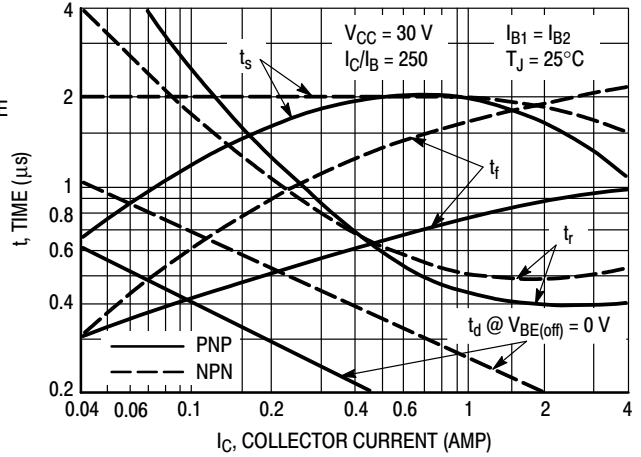


Figure 2. Switching Times

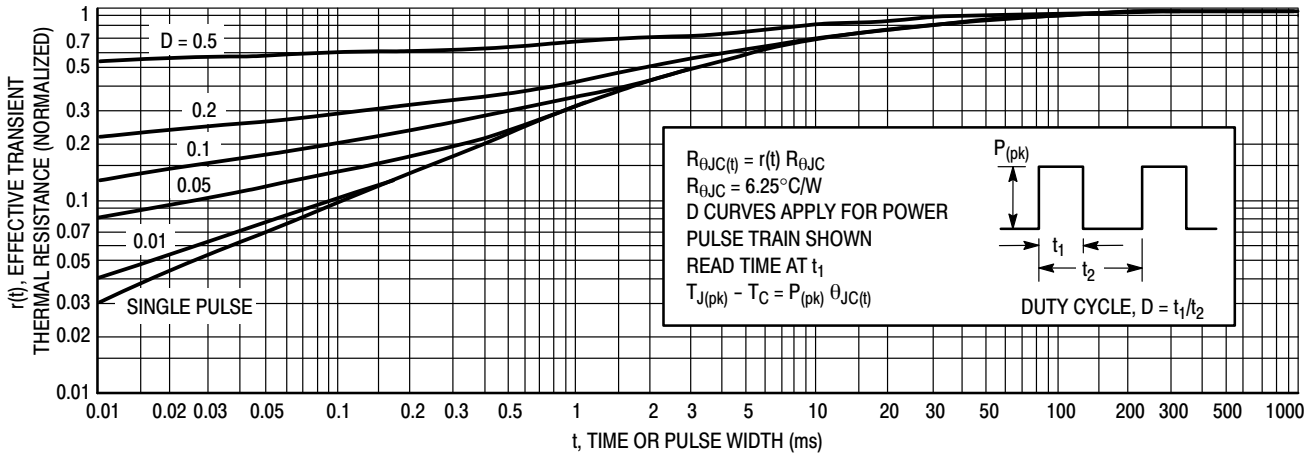
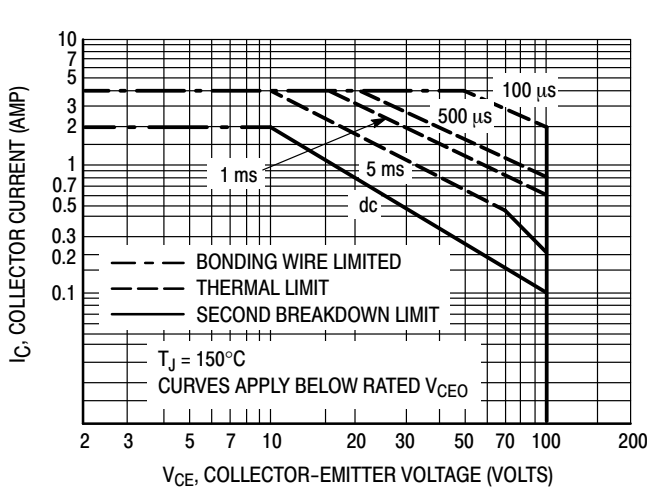


Figure 3. Thermal Response

# MJD112 (NPN), MJD117 (PNP)

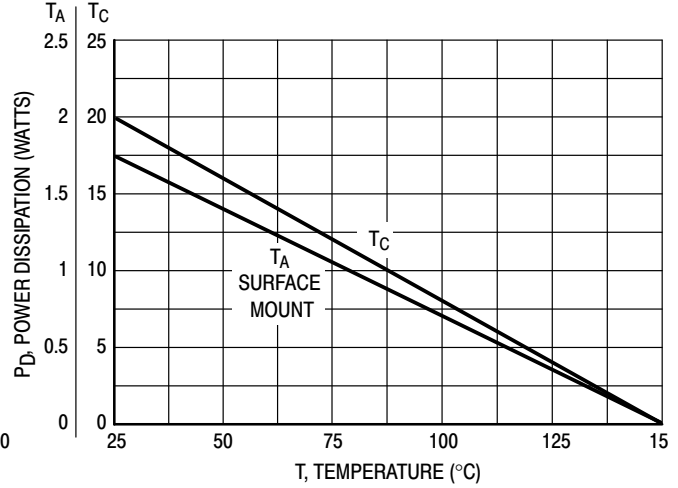
## ACTIVE-REGION SAFE-OPERATING AREA



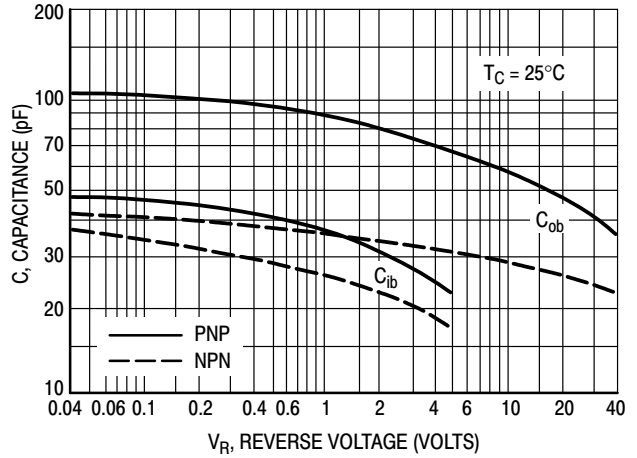
**Figure 4. Maximum Rated Forward Biased Safe Operating Area**

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figures 5 and 6 is based on  $T_{J(pk)} = 150^\circ\text{C}$ ;  $T_C$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} < 150^\circ\text{C}$ .  $T_{J(pk)}$  may be calculated from the data in Figure 4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.



**Figure 5. Power Derating**



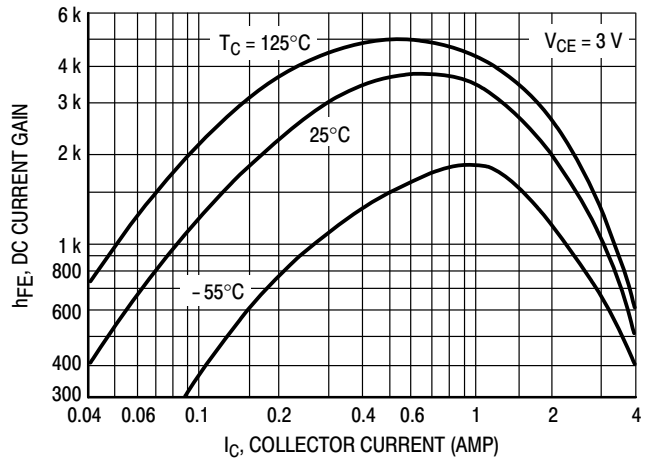
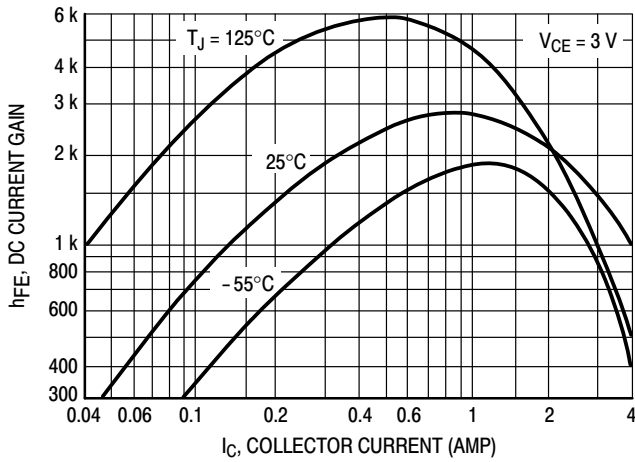
**Figure 6. Capacitance**

# MJD112 (NPN), MJD117 (PNP)

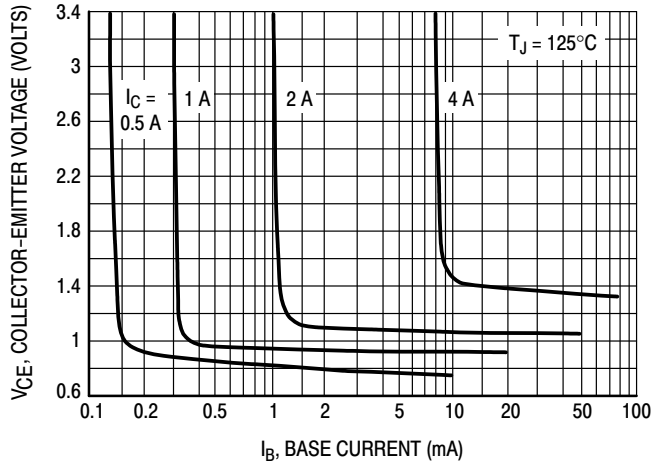
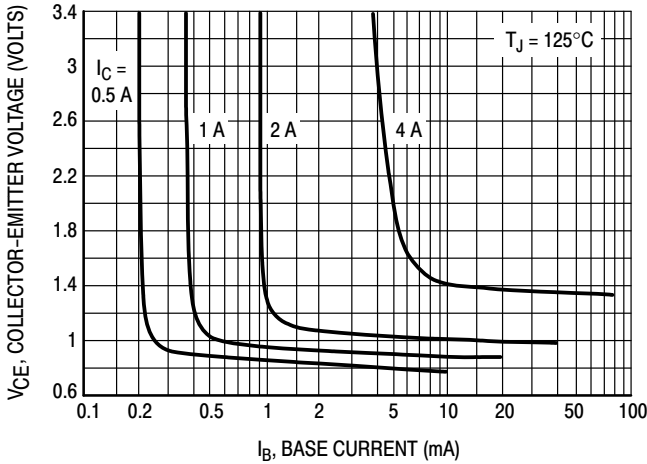
## TYPICAL ELECTRICAL CHARACTERISTICS

**NPN MJD112**

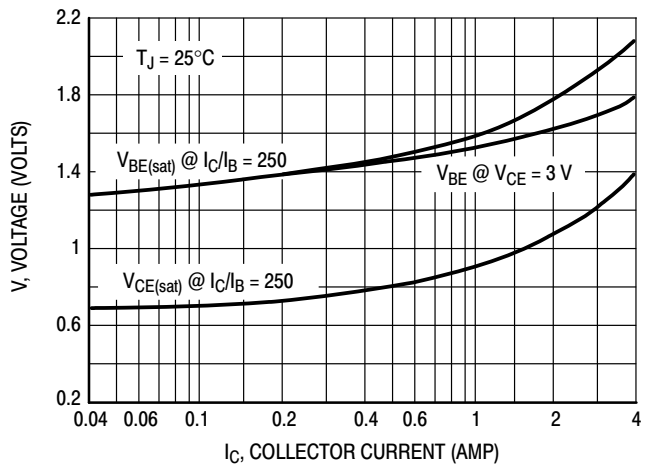
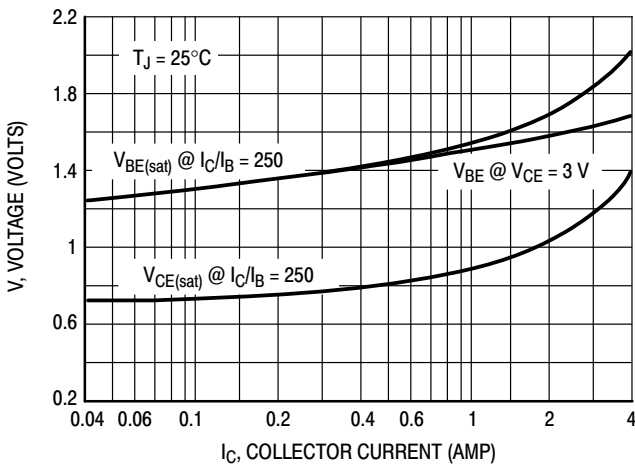
**PNP MJD117**



**Figure 7. DC Current Gain**



**Figure 8. Collector Saturation Region**

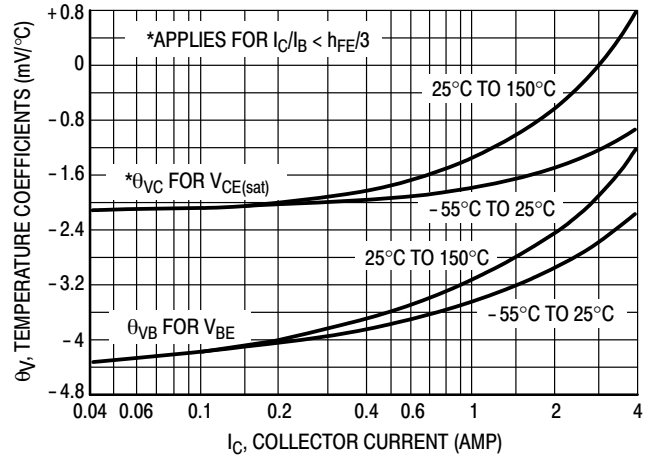
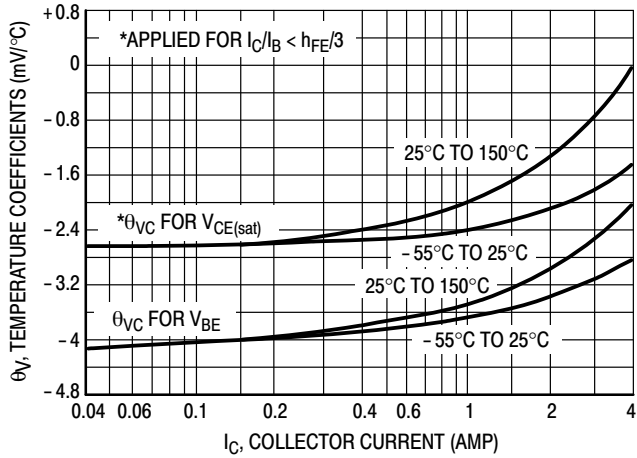


**Figure 9. "On Voltages"**

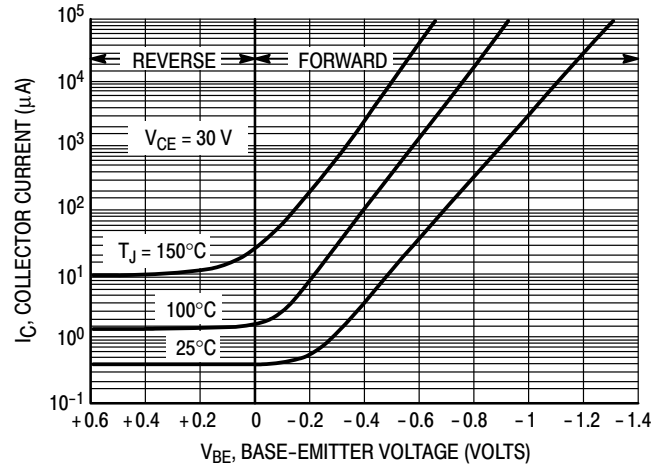
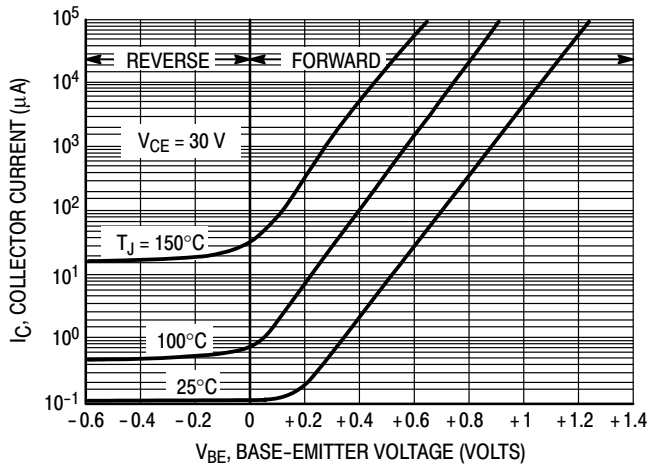
# MJD112 (NPN), MJD117 (PNP)

**NPN MJD112**

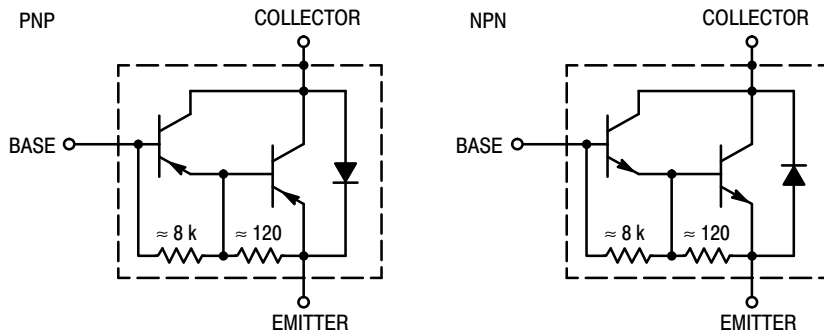
**PNP MJD117**



**Figure 10. Temperature Coefficients**



**Figure 11. Collector Cut-Off Region**



**Figure 12. Darlington Schematic**



## MJD112 (NPN), MJD117 (PNP)

### ORDERING INFORMATION

Device	Package Type	Package	Shipping <sup>†</sup>
MJD112G	DPAK (Pb-Free)	369C	75 Units / Rail
NJVMJD112G*	DPAK (Pb-Free)	369C	75 Units / Rail
MJD112-1G	DPAK-3 (Pb-Free)	369D	75 Units / Rail
MJD112RLG	DPAK (Pb-Free)	369C	1,800 Tape & Reel
MJD112T4G	DPAK (Pb-Free)	369C	2,500 Tape & Reel
NJVMJD112T4G*	DPAK (Pb-Free)	369C	2,500 Tape & Reel
MJD117G	DPAK (Pb-Free)	369C	75 Units / Rail
MJD117-1G	DPAK-3 (Pb-Free)	369D	75 Units / Rail
MJD117RLG	DPAK (Pb-Free)	369C	1,800 Tape & Reel
MJD117T4G	DPAK (Pb-Free)	369C	2,500 Tape & Reel
NJVMJD117T4G*	DPAK (Pb-Free)	369C	2,500 Tape & Reel

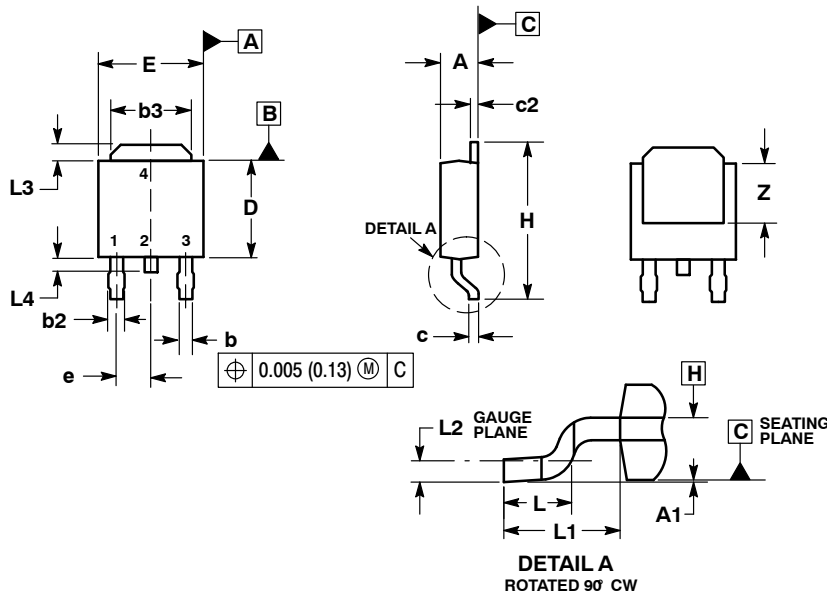
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

# MJD112 (NPN), MJD117 (PNP)

## PACKAGE DIMENSIONS

### DPAK CASE 369C ISSUE D



**NOTES:**

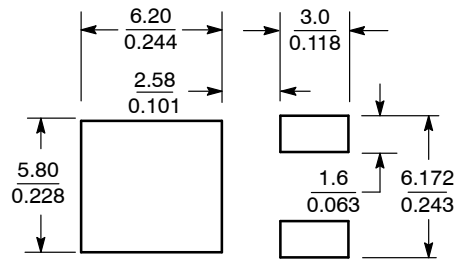
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090	BSC	2.29	BSC
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108	REF	2.74	REF
L2	0.020	BSC	0.51	BSC
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

**STYLE 1:**

- PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

### SOLDERING FOOTPRINT\*



SCALE 3:1 (mm/inches)

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.